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Declarations under Rule 4.17:

- as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))
- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))

(54) **Title:** MACHINE LEARNING FOR POSITIONING

(57) **Abstract:** Various aspects of the present disclosure relate to methods, apparatuses, and systems that support machine learning for positioning. For instance, implementations provide for direct Artificial Intelligence (AI)-based positioning and AI-assisted positioning which can be leveraged to improve User Equipment (UE) location accuracy performance. In example implementations, for direct AI/Machine Learning (ML) positioning, techniques such as fingerprinting can be leveraged by AI/ML models to obtain enhanced location accuracies, such as via measurement and environmental data. Accordingly, the present disclosure provides techniques to configure direct AI/ML positioning assistance data as well as define measurements to perform AI/ML direct positioning. Further, the present disclosure provides techniques to configure reporting criteria for nodes and/or other entities performing AI/ML direct positioning measurements.

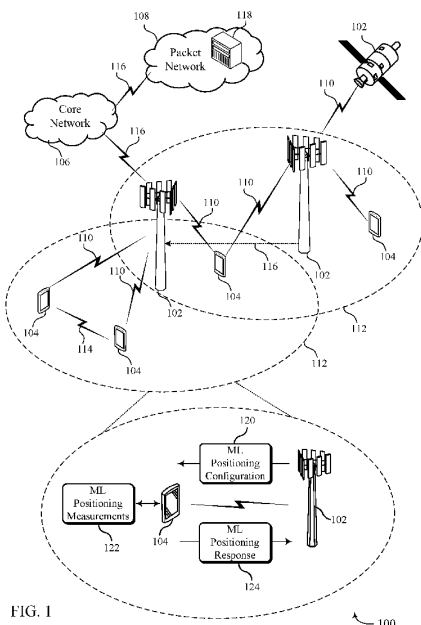


FIG. 1

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